

# EC360 GLUE WHITE

## Thermal Glue Series

A mixture of organic silicone grease and filler give the EC360® GLUE WHITE series a high thermal conductivity combined with excellent adhesion qualities. This combination makes it the perfect liquid glue for many applications. The primary use case is attaching heatsinks to RAM, Northbridge and other electrical

components. Its comparatively strong adhesion properties also make it a candidate for attaching heavier heatsinks permanently. When hardened the glue has a silicone like structure which allows a good durability also on flexible surfaces and makes it electrically insulating.

## Material Composition

Type	Percentage
Thermal Conductive Materials	40%
Silicone	35%
Fillers	25%

## Types and Configurations

Type*	Available sizes*
Tube	10 g

\* Custom configurations are available upon request, for worldwide industrial inquiries please contact us at: [sales@extremecool360.com](mailto:sales@extremecool360.com)

## Technical Properties

Properties	Unit	Value	Test method
Color	-	white	Visual
Thermal Conductivity	W/mK	2.0	ASTM D5470
Thermal Resistance	°C-in <sup>2</sup> /W	0.246	ASTM D5470
Evaporation	%	0.001	-
Bond Strength	MPa	1.8	-
Surface Drying Time(25°C)	minutes	6.0	-
Dielectric Constant	1Mhz	5.0	ASTM D 150
Usable Temperatures	°C	-60 - 250	EN 344

## Installation Recommendation

- Clean surfaces from dirt and other possible residue. If applicable, isopropyl 90% alcohol is recommended to ensure a clean surface.
- Apply a sufficient amount of glue and spread it evenly on the heatsink. The amount should be as thin as surface conditions permit.
- Position the heatsink and gently press it gently onto the surface of the chip. Wait for a minimum of 1 hour. Waiting time may vary depending on the thickness and room temperature. Now the glue should have hardened and the heatsink attached.